



Material Content Data Sheet



Sales Product Name		SAK-XC164CM-16F40F BA		Issued		1. August 2018		
MA#		MA001295788						
Package		PG-LQFP-64-4		Weight*		375.50 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	19.143	5.10	5.10	50979	50979
leadframe	non noble metal	magnesium	7439-95-4	0.174	0.05		464	
	inorganic material	silicon	7440-21-3	0.755	0.20		2010	
	non noble metal	nickel	7440-02-0	3.484	0.93		9278	
	non noble metal	copper	7440-50-8	111.722	29.75	30.93	297526	309278
wire	noble metal	gold	7440-57-5	1.871	0.50	0.50	4983	4983
encapsulation	organic material	carbon black	1333-86-4	1.142	0.30		3042	
	plastics	epoxy resin	-	30.842	8.21		82137	
	inorganic material	silicondioxide	60676-86-0	196.478	52.33	60.84	523241	608420
leadfinish	non noble metal	tin	7440-31-5	4.066	1.08	1.08	10827	10827
plating	noble metal	silver	7440-22-4	1.690	0.45	0.45	4502	4502
glue	plastics	epoxy resin	-	0.827	0.22		2202	
	noble metal	silver	7440-22-4	3.308	0.88	1.10	8809	11011
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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